

RF Inlay Smart Card Welding Head

This pressure welding head is designed for RF inlay smart card manufacturing. It ensures consistent and reliable bonding of RF components to smart card substrates.



ADDITIONAL IMAGES



Product Overview

Precision Engineering for Smart Card Production

This pressure welding head is specifically engineered for the reliable bonding of RF inlays onto smart card substrates. Its design prioritizes optimal pressure distribution and precise alignment to ensure electrical conductivity and mechanical stability. Built from durable, high-quality materials, the unit is tailored for the rigorous demands of high-volume manufacturing environments.

Technical Specifications

Performance Metrics

1 High

Alignment Precision

100 %

Durability Rating

Key Design Features

- Split design for optimal pressure distribution
- Integrated alignment holes for secure mounting
- High thermal conductivity materials
- Wear-resistant construction

Compatibility & Usage

Ideal Applications

RF Inlay Welding, Smart Card Manufacturing, High-Volume Production

Equipment Compatibility

Yes